

Abstract of the Disclosure

A thin, lightweight retention mechanism with a spring force holds an integrated circuit package to a circuit board. The retention mechanism consists of a pressure plate, a backing plate, and a fastening means for applying a deforming
5 force to the plates, such as screws and nuts. The plates are paraboloid or dish-shaped and made of an elastically deformable material, such as steel. The fastening means simultaneously applies deforming forces to the peripheries of the plates to create a continuous spring force to effect electrical continuity between the integrated circuit package and the circuit board. In addition, a method of testing the retention
10 mechanism and a method of assembling the retention mechanism are disclosed.

"Express Mail" mailing label number: EL709303436US

Date of Deposit: December 8, 2000

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.